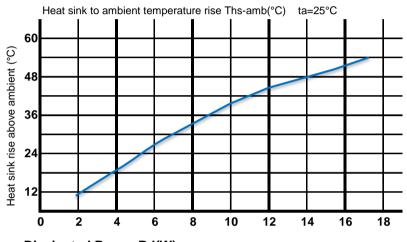


The thermal data table

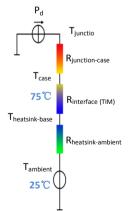
Pd=Pe x (1-ηL)		Heat sink to ambient thermal resistance Rhs-amb(°C/W)	Heat sink to ambient temperature rise Ths-amb(°C)
		Orbit-90	
Dissipated Power Pd(W)	2	5.15	10.7
	4	4.75	19.8
	6	4.47	28
	8	4.11	34.5
	10	3.96	41.6
	12	3.51	44.5
	15	3.06	48.9



Dissipated Power Pd(W)

- * Please be aware the dissipated power Pd is not the same as the electrical power Pe of a LED module.
- *To calculate the dissipated power please use the following formula: $Pd = Pe \times (I \eta L)$.
 - Pd Dissipated power ; Pe Electrical power ; $\eta L =$ Light effciency of the LED module;
- *The aluminum substrate side of the package outer shell is thermally connected to the heat sink via TIM (Thermal interface material).
- MingFa recommends the use of a high thermal conductive interface between the LED module and the LED cooler.

Either thermal grease, A thermal pad or a phase change thermal pad thickness 0.1-0.15mm is recommended.



- *Thermal resistance is a heat property and a measurement of a temperature difference by which an object or material resists a heat flow.
- Geometric shapes are different, the thermal resistance is different. Formula: $\theta = (Ths Ta)/Pd$
- θ Thermal Resistance [°C/M]; Ths Heatsink temperature; Ta Ambient temperature;
- *The thermal resistance between the junction section of the light-emitting diode and the aluminum substrate side of the package outer
- shell is $R_{junction-case}$, the thermal resistance of the TIM outside the package is $R_{interface \, (TIM)}$ [°C/M], the thermal resistance with the
- heat sink is $R_{heatsink-ambient}$ [°C/W], and the ambient temperature is $T_{ambient}$ [°C].
- *Thermal resistances outside the package $R_{interface \, (TIM)}$ and $R_{heatsink-ambient}$ can be integrated into the thermal resistance $R_{case-ambient}$ at this point. Thus, the following formula is also used:
- $T_{junction} = (R_{junction-case} + R_{case-ambient}) \cdot Pd + T_{ambient}$